



GENERAL DESCRIPTION



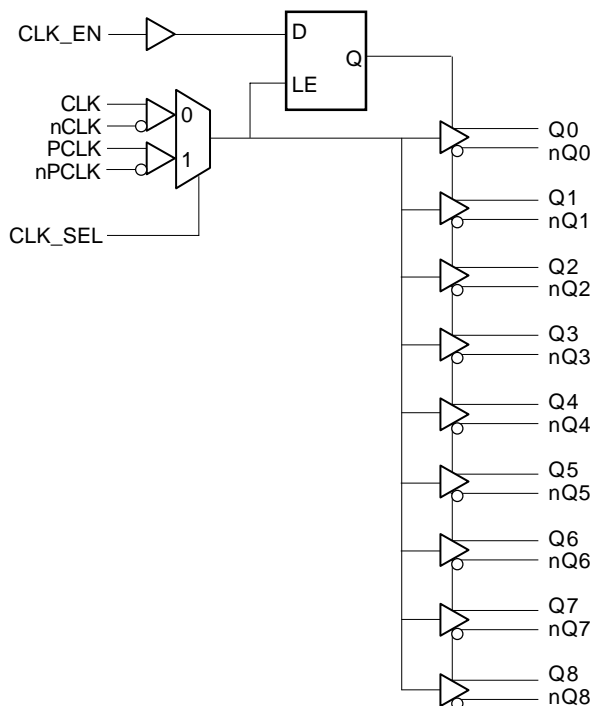
The ICS8521 is a low skew, 1-to-9 3.3V Differential-to-LVHSTL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS8521 has two selectable clock inputs. The CLK, nCLK pair can accept most standard differential input levels. The PCLK, nPCLK pair can accept LVPECL, CML, or SSTL input levels. The clock enable is internally synchronized to eliminate runt pulses on the outputs during asynchronous assertion/deassertion of the clock enable pin.

Guaranteed output skew, part-to-part skew and crossover voltage characteristics make the ICS8521 ideal for today's most advanced applications, such as IA64 and static RAMs.

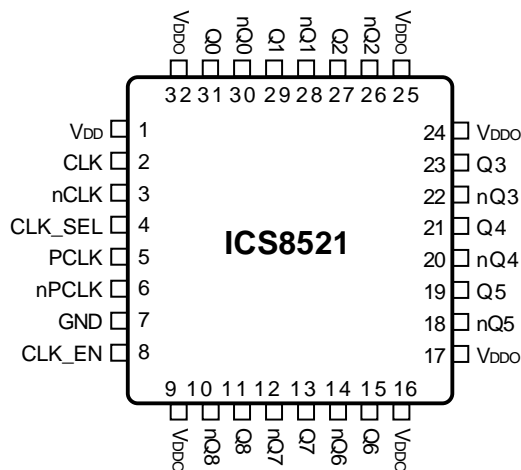
FEATURES

- 9 LVHSTL outputs
- Selectable CLK, nCLK or LVPECL clock inputs
- CLK, nCLK pair can accept the following differential input levels: LVDS, LVPECL, LVHSTL, SSTL, HCSL
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- Maximum output frequency up to 500MHz
- Output skew: 50ps (maximum)
- Part-to-part skew: 250ps (maximum)
- Propagation delay: 1.8ns (maximum)
- $V_{OH} = 1.2V$ (maximum)
- 3.3V core, 1.8V output operating supply voltages
- 0°C to 70°C ambient operating temperature
- Industrial temperature information available upon request

BLOCK DIAGRAM



PIN ASSIGNMENT



32-Lead LQFP
7mm x 7mm x 1.4mm Package Body
Y Package
Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1	V _{DD}	Power		Positive supply pin. Connect to 3.3V.
2	CLK	Input	Pulldown	Non-inverting differential clock input.
3	nCLK	Input	Pullup	Inverting differential clock input.
4	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects PCLK, nPCLK inputs. When LOW, selects CLK, nCLK. LVTTTL / LVCMOS interface levels.
5	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
6	nPCLK	Input	Pullup	Inverting differential LVPECL clock input.
7	GND	Power		Power supply ground. Connect to ground.
8	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVCMOS /LVTTTL interface levels.
9, 16, 17, 24, 25, 32	V _{DDO}	Power		Output supply pins. Connect to 1.8V.
10, 11	nQ8, Q8	Output		Differential output pair. LVHSTL interface level.
12, 13	nQ7, Q7	Output		Differential output pair. LVHSTL interface level.
14, 15	nQ6, Q6	Output		Differential output pair. LVHSTL interface level.
18, 19	nQ5, Q5	Output		Differential output pair. LVHSTL interface level.
20, 21	nQ4, Q4	Output		Differential output pair. LVHSTL interface level.
22, 23	nQ3, Q3	Output		Differential output pair. LVHSTL interface level.
26, 27	nQ2, Q2	Output		Differential output pair. LVHSTL interface level.
28, 29	nQ1, Q1	Output		Differential output pair. LVHSTL interface level.
30, 31	nQ0, Q0	Output		Differential output pair. LVHSTL interface level.

NOTE: *Pullup* and *Pulldown* refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance	CLK, nCLK, PCLK, nPCLK				4	pF
		CLK_EN, CLK_SEL				4	pF
R _{PULLUP}	Input Pullup Resistor				51		KΩ
R _{PULLDOWN}	Input Pulldown Resistor				51		KΩ



TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs			Outputs	
CLK_EN	CLK_SEL	Selected Sourced	Q0 thru Q8	nQ0 thru nQ8
0	0	CLK, nCLK	Disabled; LOW	Disabled; HIGH
0	1	PCLK, nPCLK	Disabled; LOW	Disabled; HIGH
1	0	CLK, nCLK	Enabled	Enabled
1	1	PCLK, nPCLK	Enabled	Enabled

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1.

In the active mode, the state of the outputs are a function of the CLK, nCLK and PCLK, nPCLK inputs as described in Table 3B.

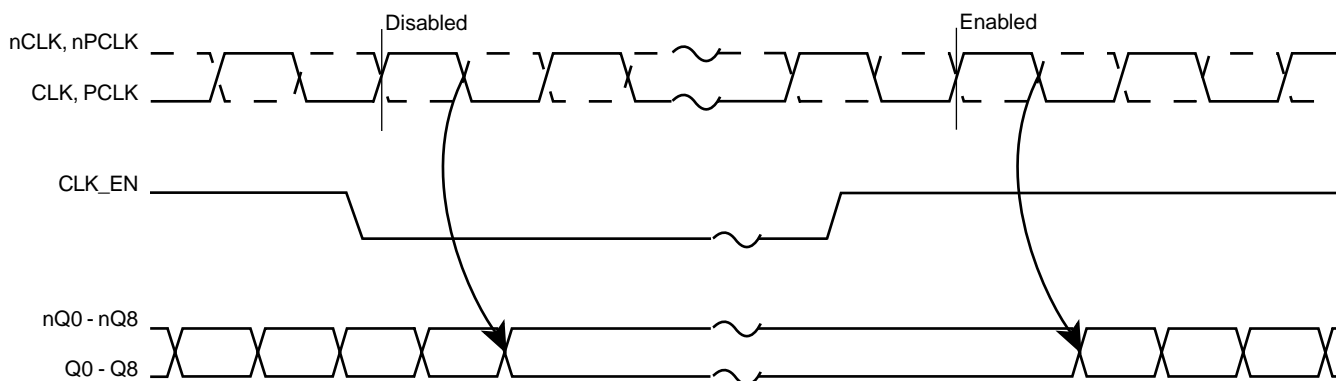


FIGURE 1: CLK_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

Inputs		Outputs		Input to Output Mode	Polarity
CLK or PCLK	nCLK or nPCLK	Q0 thru Q8	nQ0 thru nQ8		
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information section on page 8, Figure 9, which discusses wiring the differential input to accept single ended levels.



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DDX}	4.6V
Inputs, V_I	-0.5V to $V_{DD} + 0.5V$
Outputs, V_O	-0.5V to $V_{DDO} + 0.5V$
Package Thermal Impedance, θ_{JA}	47.9°C/W
Storage Temperature, T_{STG}	-65°C to 150°C

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
V_{DDO}	Output Supply Voltage		1.6	1.8	2.0	V
I_{DD}	Power Supply Current			60	80	mA

TABLE 4B. LVCMOS DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	CLK_EN, CLK_SEL		2		3.765	V
V_{IL}	CLK_EN, CLK_SEL		-0.3		0.8	V
I_{IH}	Input High Current	CLK_EN $V_{IN} = V_{DD} = 3.465V$			5	μA
		CLK_SEL $V_{IN} = V_{DD} = 3.465V$			150	μA
I_{IL}	Input Low Current	CLK_EN $V_{IN} = 0V, V_{DD} = 3.465V$	-150			μA
		CLK_SEL $V_{IN} = 0V, V_{DD} = 3.465V$	-5			μA

TABLE 4C. DIFFERENTIAL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK $V_{IN} = V_{DD} = 3.465V$			150	μA
		nCLK $V_{IN} = V_{DD} = 3.465V$			5	μA
I_{IL}	Input Low Current	CLK $V_{IN} = 0V, V_{DD} = 3.465V$	-5			μA
		nCLK $V_{IN} = 0V, V_{DD} = 3.465V$	-150			μA
V_{PP}	Peak-to-Peak Input Voltage		0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2		0.5		$V_{DD} - 0.85$	V

NOTE 1: For single ended applications, the maximum input voltage for CLK and nCLK is $V_{DD} + 0.3V$.

NOTE 2: Common mode voltage is defined as V_{IH} .



TABLE 4D. LVPECL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	PCLK $V_{DD} = V_{IN} = 3.465V$			150	μA
		nPCLK $V_{DD} = V_{IN} = 3.465V$			5	μA
I_{IL}	Input Low Current	PCLK $V_{DD} = 3.465V$, $V_{IN} = 0V$	-5			μA
		nPCLK $V_{DD} = 3.465V$, $V_{IN} = 0V$	-150			μA
V_{PP}	Peak-to-Peak Input Voltage		0.3		1	V
V_{CMR}	Common Mode Input Voltage; NOTE 1, 2		1.5		V_{DD}	V

NOTE 1: Common mode voltage is defined as V_{IH} .

NOTE 2: For single ended applications, the maximum input voltage for PCLK and nPCLK is $V_{DD} + 0.3V$.

TABLE 4E. LVHSTL DC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		1.0		1.2	V
V_{OL}	Output Low Voltage; NOTE 1		0		0.4	V
V_{OX}	Output Crossover Voltage		$40\% \times (V_{OH} - V_{OL}) + V_{OL}$		$60\% \times (V_{OH} - V_{OL}) + V_{OL}$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.1	V

NOTE 1: Outputs terminated with 50Ω to ground.

TABLE 5. AC CHARACTERISTICS, $V_{DD} = 3.3V \pm 5\%$, $V_{DDO} = 1.8V \pm 0.2V$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Maximum Output Frequency				500	MHz
t_{PD}	Propagation Delay; NOTE 1	$f \leq 250MHz$	1		1.8	ns
$tsk(o)$	Output Skew; NOTE 2, 4				50	ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4				250	ps
t_R	Output Rise Time	20% to 80% @ 50MHz	300		700	ps
t_F	Output Fall Time	20% to 80% @ 50MHz	300		700	ps
odc	Output Duty Cycle		48		52	%

All parameters measured at 250MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

Measured from $V_{DD}/2$ to the output differential crossing point for single ended input levels.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

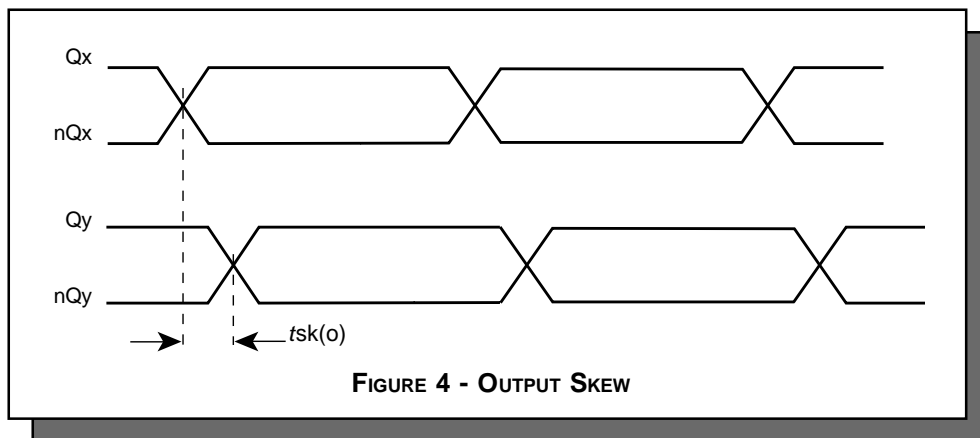
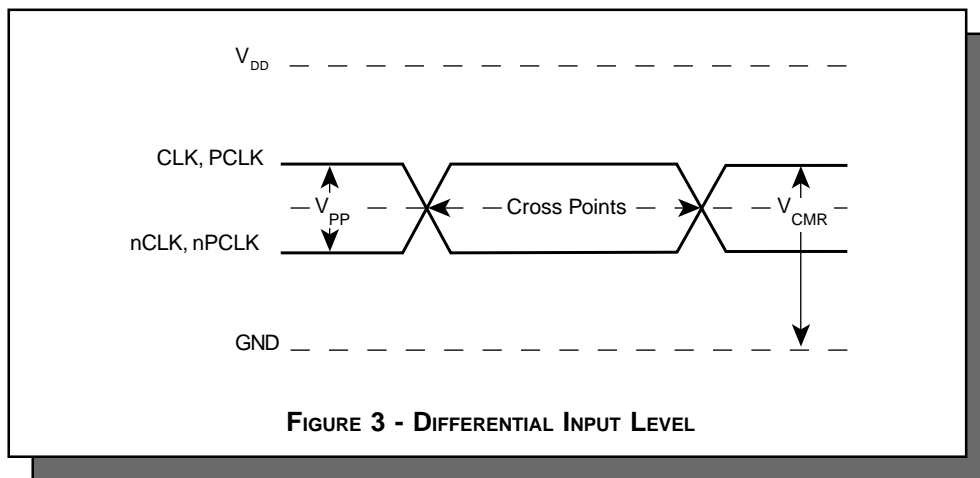
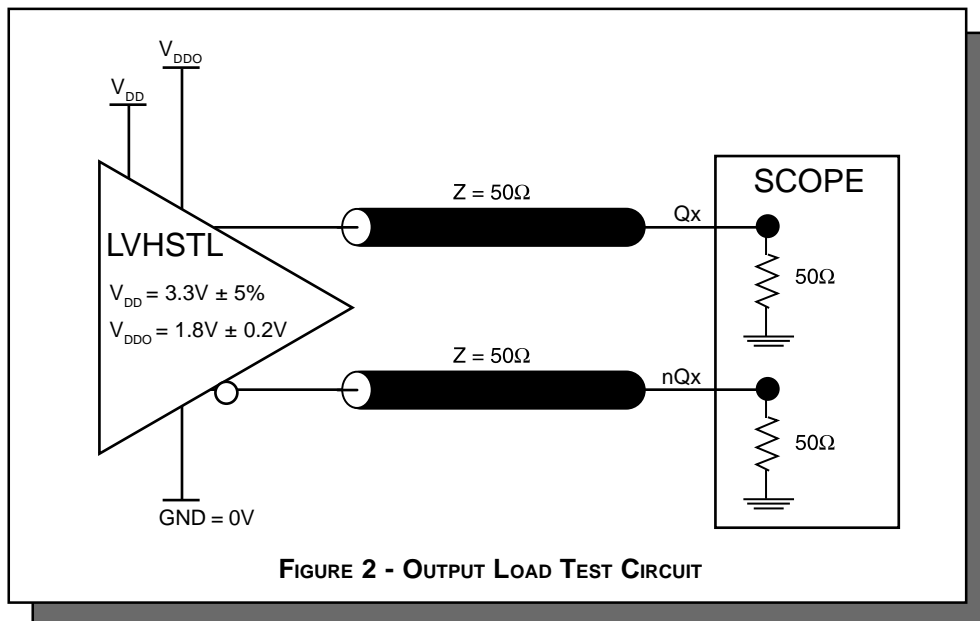
Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the output are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



PARAMETER MEASUREMENT INFORMATION



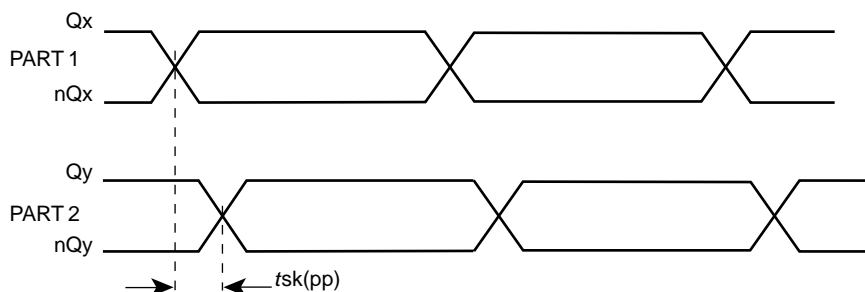


FIGURE 5 - PART-TO-PART SKEW



FIGURE 6 - INPUT AND OUTPUT RISE AND FALL TIME

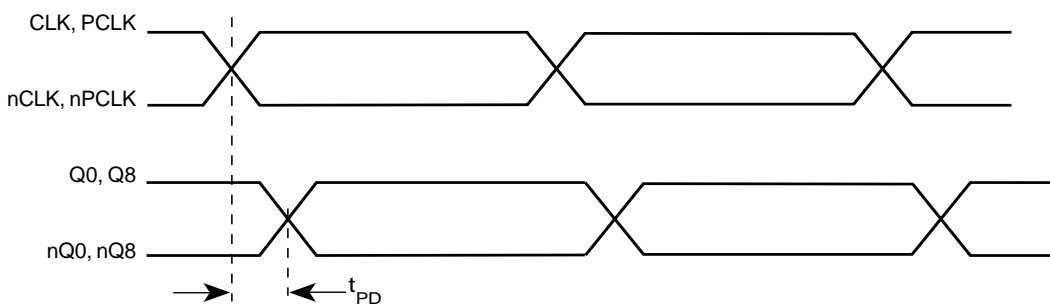


FIGURE 7 - PROPAGATION DELAY

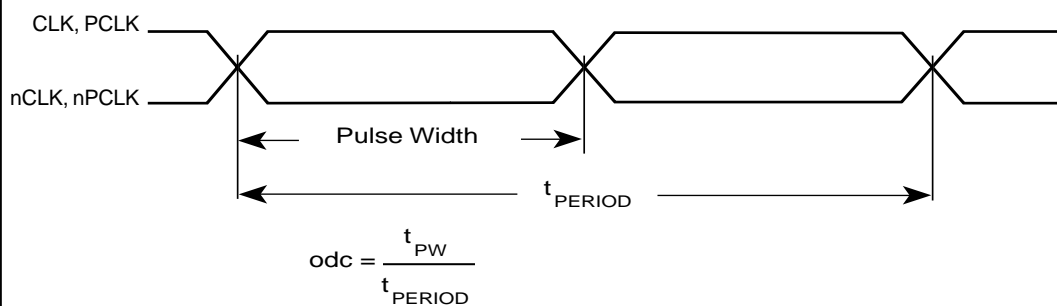


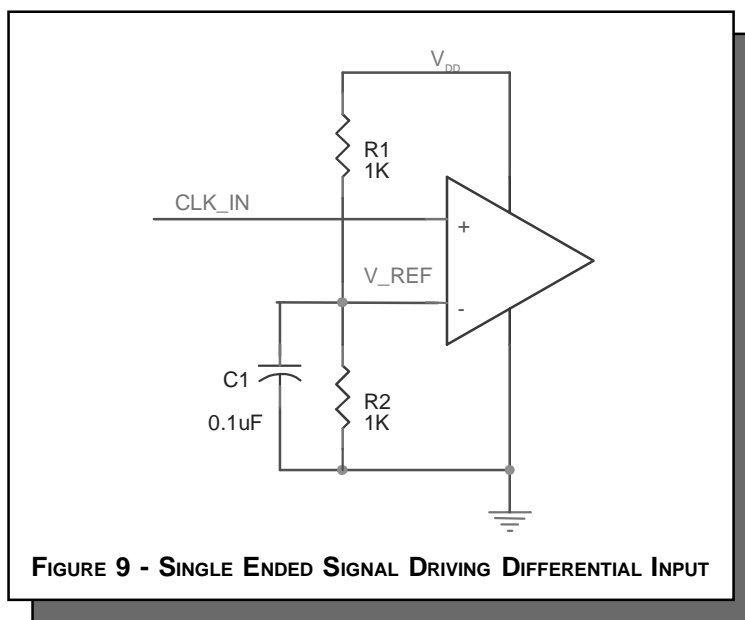
FIGURE 8 - odc & t_{PERIOD}



APPLICATION INFORMATION

WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 9 shows how the differential input can be wired to accept single ended levels. The reference voltage $V_{REF} \approx V_{DD}/2$ is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and $V_{DD} = 3.3V$, V_{REF} should be 1.25V and $R2/R1 = 0.609$.





POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS8521. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS8521 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{DD} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{DD_MAX} * I_{DD_MAX} = 3.465V * 80mA = 277.2mW$
- Power (outputs)_{MAX} = **32mW/Loaded Output pair**
If all outputs are loaded, the total power is $9 * 32mW = 288mW$

$$\text{Total Power}_{MAX} (3.465V, \text{ with all outputs switching}) = 277.2mW + 288mW = 565.2mW$$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = junction-to-ambient thermal resistance

Pd_total = Total device power dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 42.1°C/W per Table 6 below. Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ C + 0.565W * 42.1^\circ C/W = 93.8^\circ C. \text{ This is well below the limit of } 125^\circ C$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance θ_{JA} for 32-pin LQFP, Forced Convection

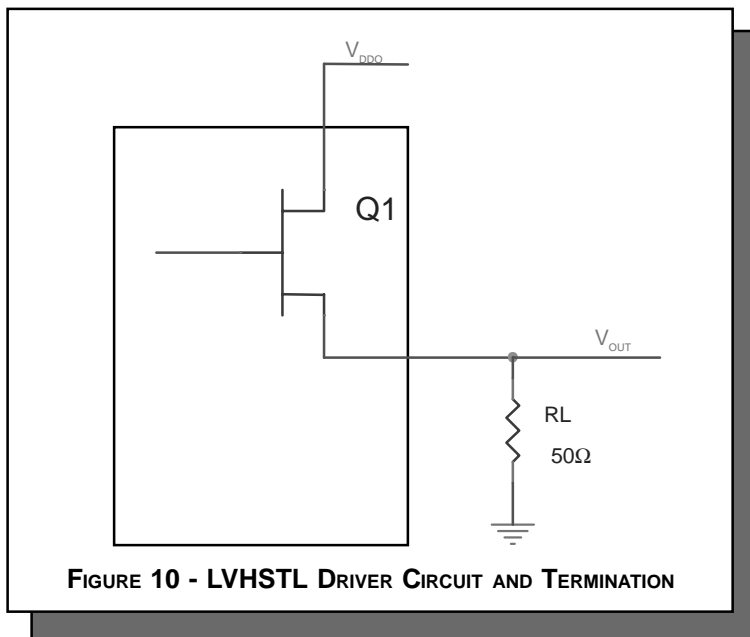
θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVHSTL output driver circuit and termination are shown in *Figure 10*.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load.

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = (V_{OH_MAX} / R_L) * (V_{DD_MAX} - V_{OH_MAX})$$

$$Pd_L = (V_{OL_MAX} / R_L) * (V_{DD_MAX} - V_{OL_MAX})$$

$$Pd_H = (1.2V / 50\Omega) * (2V - 1.2V) = \mathbf{19.2mW}$$

$$Pd_L = (0.4V / 50\Omega) * (2V - 0.4V) = \mathbf{12.8mW}$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = \mathbf{32mW}$$



RELIABILITY INFORMATION

TABLE 6. θ_{JA} vs. AIR FLOW TABLE

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8521 is: 944



Integrated
Circuit
Systems, Inc.

ICS8521

Low SKEW, 1-TO-9
DIFFERENTIAL-TO-LVHSTL FANOUT BUFFER

PACKAGE OUTLINE - Y SUFFIX

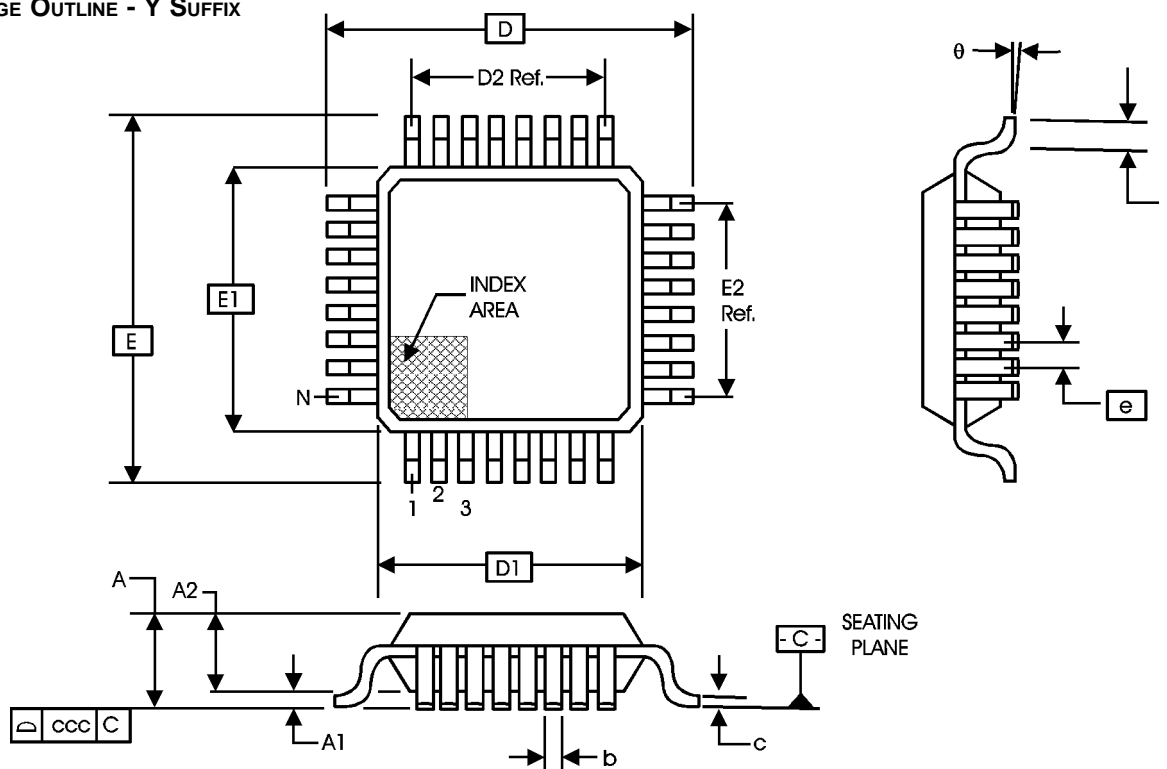


TABLE 6. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS			
SYMBOL	BBA		
	MINIMUM	NOMINAL	MAXIMUM
N	32		
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.30	0.37	0.45
c	0.09	--	0.20
D	9.00 BASIC		
D1	7.00 BASIC		
D2	5.60 Ref.		
E	9.00 BASIC		
E1	7.00 BASIC		
E2	5.60 Ref.		
e	0.80 BASIC		
L	0.45	0.60	0.75
θ	0°	--	7°
ccc	--	--	0.10

Reference Document: JEDEC Publication 95, MS-026



Integrated
Circuit
Systems, Inc.

ICS8521

LOW SKEW, 1-TO-9
DIFFERENTIAL-TO-LVHSTL FANOUT BUFFER

TABLE 7. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS8521BY	ICS8521BY	32 Lead LQFP	250 per tray	0°C to 70°C
ICS8521BYT	ICS8521BY	32 Lead LQFP on Tape and Reel	1000	0°C to 70°C

While the information presented herein has been checked for both accuracy and reliability, Integrated Circuit Systems, Incorporated (ICS) assumes no responsibility for either its use or for infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial applications. Any other applications such as those requiring extended temperature range, high reliability, or other extraordinary environmental requirements are not recommended without additional processing by ICS. ICS reserves the right to change any circuitry or specifications without notice. ICS does not authorize or warrant any ICS product for use in life support devices or critical medical instruments.